

MOUNTING METHOD FOR WORKPIECE HAVING BUMP, AND MOUNTING BOARD

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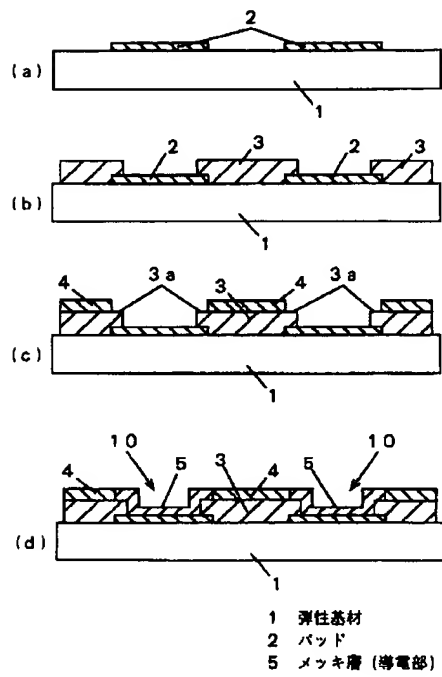
Abstract

PROBLEM TO BE SOLVED: To provide a mounting method for workpieces with bumps, and a mounting board, capable of making a heating process unnecessary, capable of sticking the bumps of a work having bumps onto the pads of a board easily, and capable of dealing with even high-density and fine pads and bumps.

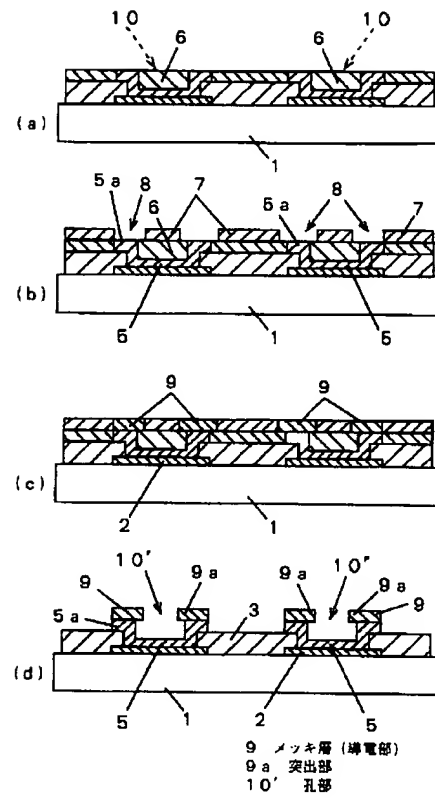
SOLUTION: A conductive part composed of a first plated layer 5 and a second plated layer is formed on a pad 2 of a base material 1. The swollen parts 13b of the bumps 13 of a work having bumps are fitted into the holes 10' of the conductive part forcedly, and the projecting parts 9a of the conductive part are hooked and fixed to the edges 131b of the swollen part 13b. Consequently, it becomes possible to prevent the bumps 13 from coming off out of the holes 10', and to bring them into contact with the conductive part firmly as well.

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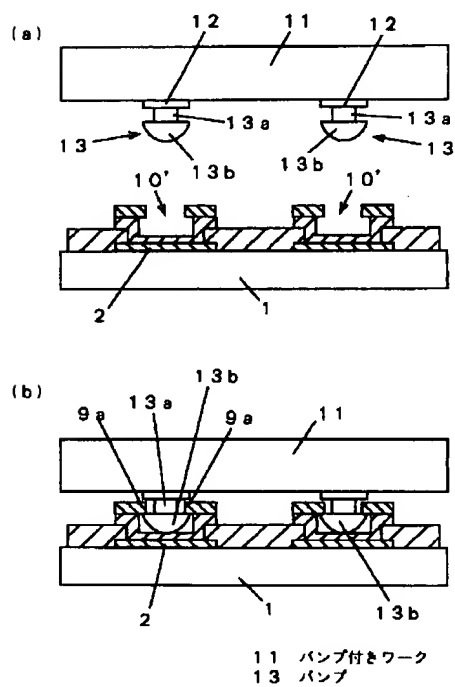
【図1】



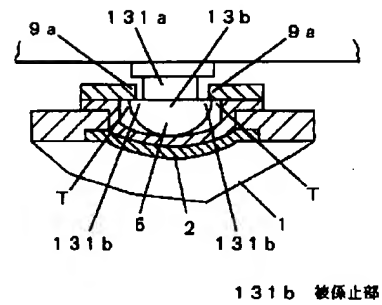
【図2】



【図3】

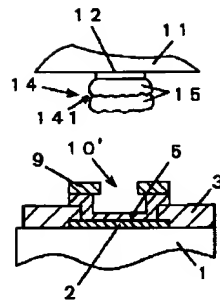


【図4】

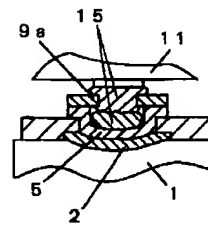


【図5】

(a)



(b)



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